

Available uniform resist coating to substrate cross/slope section Equipment for development of MEMS/Micromachine

Feature

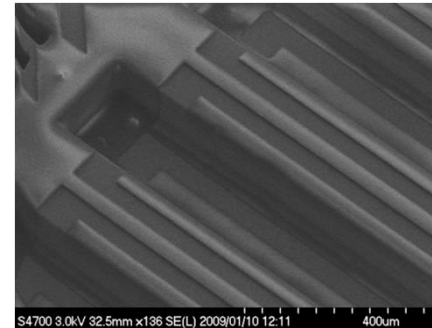
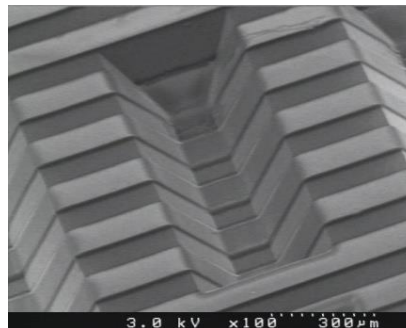
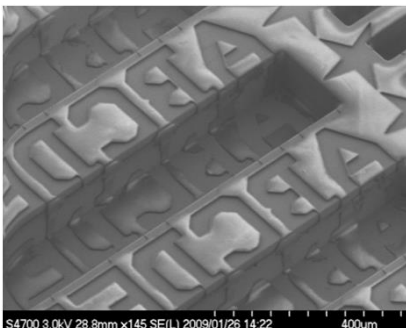
- Available uniform resist coating to substrate cross/slope section by controlling stage and airflow
- Available low-viscosity resist lamination to patterned substrate due to implemented high stiffness and high speed stage
- Suitable for experimental/developmental use
- Vacuum chucks including heater are standard
- Available recipe registration of complicated procedure and parameter setting
Easy operation helps to improve productivity/repeatability
- Touch-panel display is adopted to control all functions and monitor the system



Application:

- Trial/Development/Mass-production of MEMS devices
- Thick Film Resist Coating
- Solid Wiring to Semiconductor, etc.
- Resist embedding and flattening
- Ashing for Photoresist
- Ashing for Organic Silicon Film

This product is jointly developed by Prof. Sasaki and Assoc. Prof. Kumagai at Toyota Technological Institute.



An example of Diagonal Exposure patterning to substrate

Available Customized manufacture for your needs. Please contact us.